

Eclipse XT

Highly Configurable Scalable Pick-and-Place Handler




Automotive



Mobility



IoT/IoV & Optoelectronics



Computing & Network



Industrial & Medical



Consumer

Productivity

- Up to 13,000 UPH
- Parallelism x1 to x16
- Output bins: 3 auto, 3 manual
- 3x3 mm to 80x80 mm package handling
- Passive SLK and device kit compatible with competitors'
- Chamberless Tri-Temp; No LN₂

Differentiation

- Ultra fast T-Core Active Thermal Control
- 800 W DUT power dissipation (with Tri-Temp option)
- Tight guard band for Start of Test (with load board/ socket thermal conditioning option)
- NIST traceable thermal calibration
- Configurable SLK x1 to x4 with multiple pitches (Tri-Temp only)
- Field upgradeable to Ambient/Hot ATC or Tri-Temp ATC (for passive configuration)
- Force convective and chiller based cooling system - high reliability

- Ambient to 130°C (Standard)
- Tri-temp range -55°C to +155°C
- Ultra fast T-Core Active Thermal Control
- Low to 800 W power applications
- OSAT friendly standard process flow and device kits compatible

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Specifications

Platform

Media

- JEDEC trays

Input and Sorts

- 3 - Automated sort bins
- 3 - Manual trays
- Continuous load/unload

Test Site

- x1 to x16 (x32 road map)

Plunge Force

- 250 Kgf
- 500 Kgf (optional)

Index Time*

- < 800 ms

Throughput*

- 13,000 UPH

Features and Options

- NVcore vision In-Socket part detection
- Vision 2DID, u2DID
- Auto Retest
- Manual RFID
- DUT rotation
- 500 Kgf socket force
- DOOP input shuttle
- Auto contactor cleaning

Temperature Range

- Passive: Ambient to 130°C (155°C option)
- Ambient/Hot ATC: Ambient to 130°C (155°C option)
- Tri-Temp ATC: -40°C to 130°C (-55°C to 155°C option)

Thermal (Base)*

- Best in class Active Thermal Control with 50+ patents
- +/- 1°C temperature accuracy at the thermal head
- Hot soak station (cold soak on thermal head)
- Power and DUT temperature feedback loop available
- NIST traceable thermal calibration
- Chamberless test site
- Temperature ramp up to 100°C per second at thermal head

T-Core Thermal Options

- Device power feedback loop
- Device diode temperature feedback loop
- Load board/socket thermal conditioning (LBC)
- Socket thermal conditioning (DTM)
- Liquid and mechanical thermal interface
- Force convective or HFE chiller based cooling system for ATC
- Highly configurable SLK x1 to x4 test parallelism in multiple x,y pitches

Tester Interface

- Load board compatibility: (X and Y pitch)
- Docking height 990 to 1,178 mm
- RS 232, GPIB and P849

ESD Control

- Decay: 1,000 V to 100 V in 10 s
- Balance: ± 30 V
- Enhanced Decay Option: 1,000 V to 100 V in 5 s

User Interface

- Windows-based

Power Requirements

- 200-230 VAC, 50/60Hz, Single Phase, 30 A
- Additional: 30 A with T-Core

Change Kit

Device Types

- QFP, TQFP, TSOP, SOIC, CSP, BGA, QFN, WLCSP and others
- OSAT kit-compatible
- Passive device kits and SLK's compatible with competitors'

Package Size

- Minimum: 3 x 3 mm
- Maximum: 80 x 80 mm

Kit Changeover

- < 15 minutes typical

Contactors

- Cohu offers contact sockets for all package versions and application

OSAT-Compatible

- Reuse existing OSAT kits
- Reuse existing Passive kits and SLKs

* Consult factory for specific applications.

** Temperature accuracy typically better with T-Core.

Specifications subject to change without notice. For detailed performance specifications, please contact Cohu.